

KLT-MAA44-IMX317 V1.0**Sony IMX317 MIPI Interface M12 Auto Focus Camera Module**

Front View



Back View

Specifications

Camera Module No.	KLT-MAA44-IMX317 V1.0
Resolution	8.51MP
Image Sensor	IMX317
Sensor Type	1/2.5"
Pixel Size	1.62 μm x 1.62 μm
EFL	3.38 mm
F.NO	2.20
Pixel	3840 x 2160
View Angle	85.8°(DFOV) 77.5°(HFOV) 48.8°(VFOV)
Lens Dimensions	18.00 x 18.00 x 16.30 mm
Module Size	33.00 x 22.00 mm
Module Type	Auto Focus
Interface	MIPI
Auto Focus VCM Driver IC	DW9714P
Lens Type	650nm IR Cut
Operating Temperature	-10°C to +75°C
Mating Connector	AXE530124

KLT-MAA44-IMX317 V1.0**Sony IMX317 MIPI Interface M12 Auto Focus Camera Module**

Top View



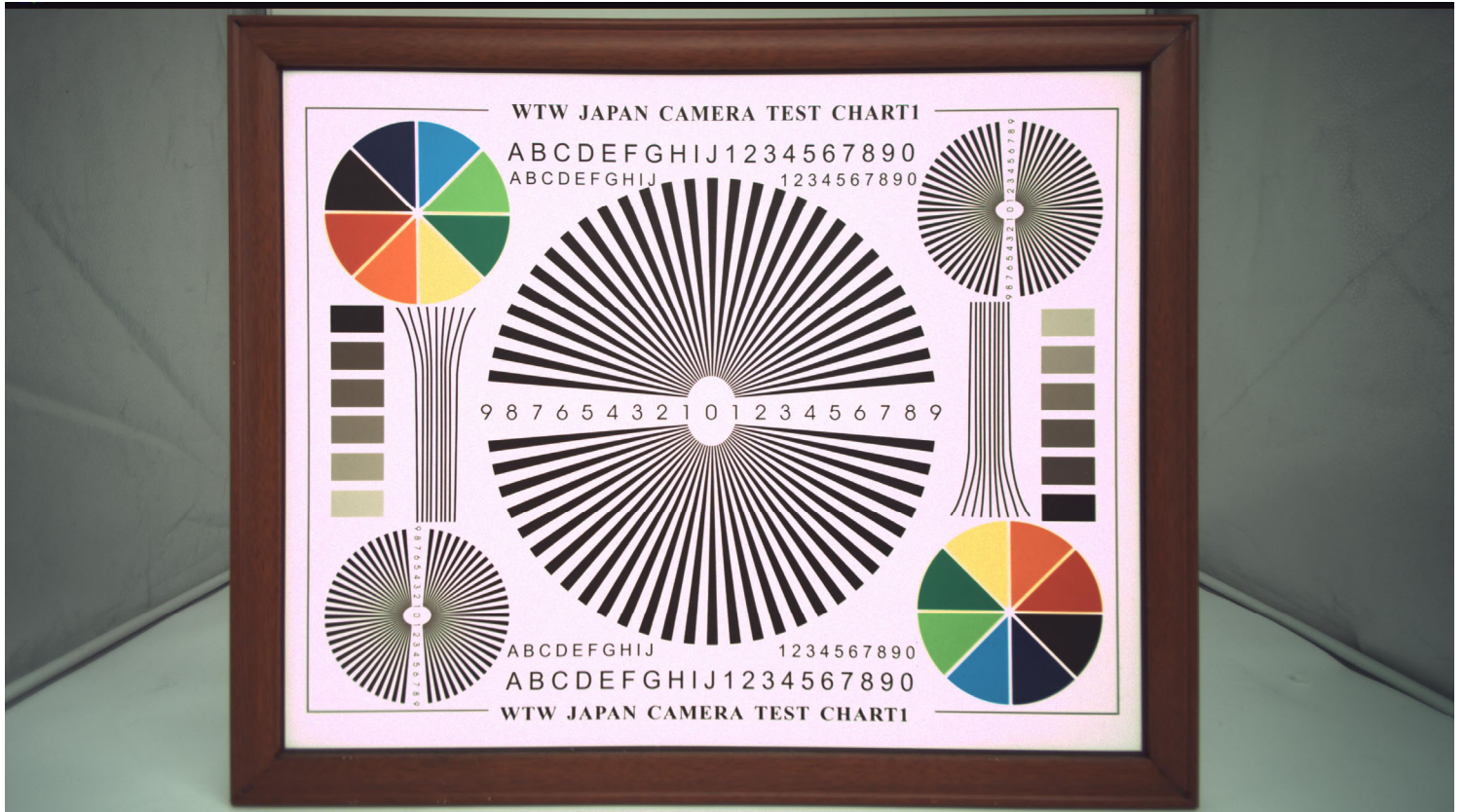
Side View

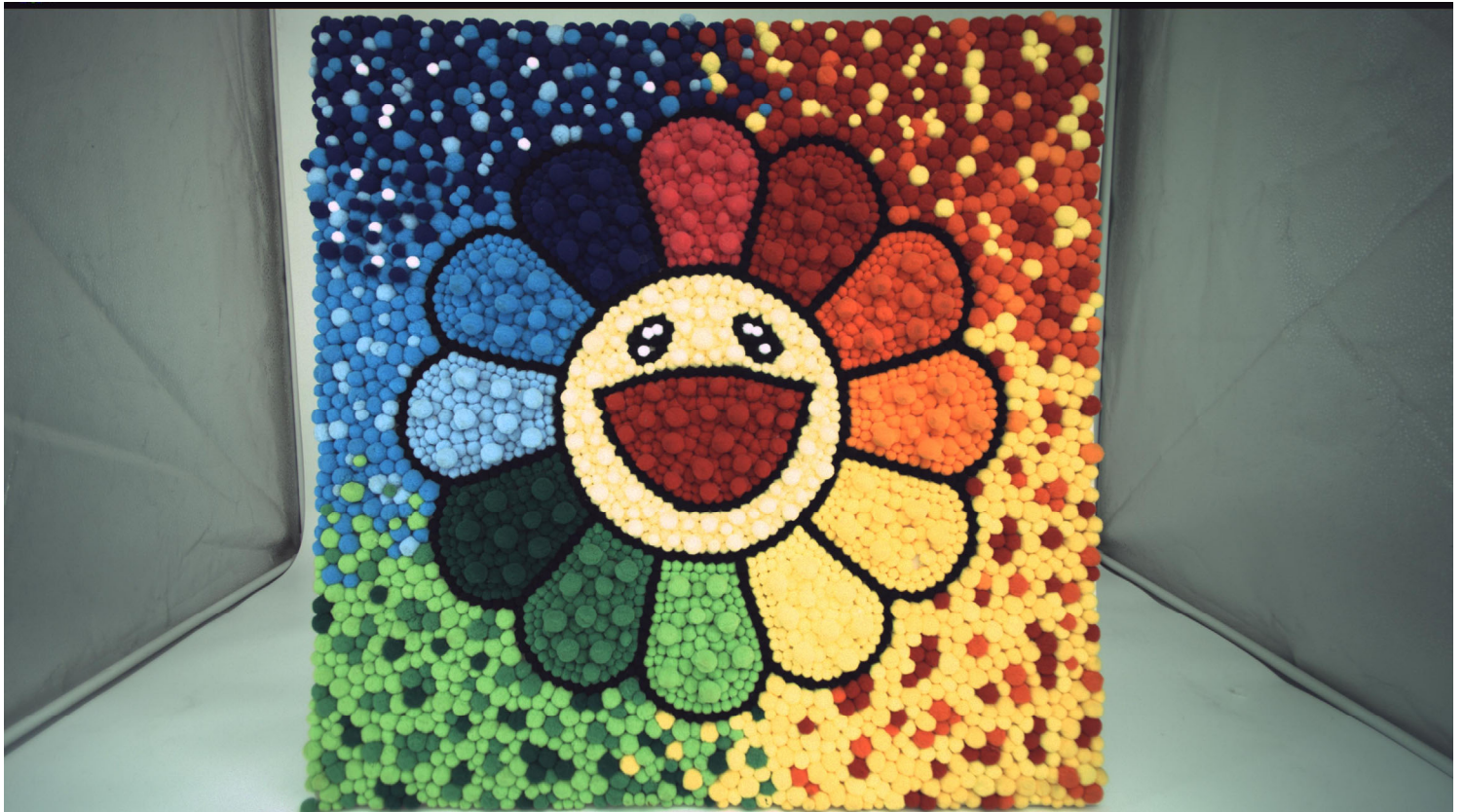
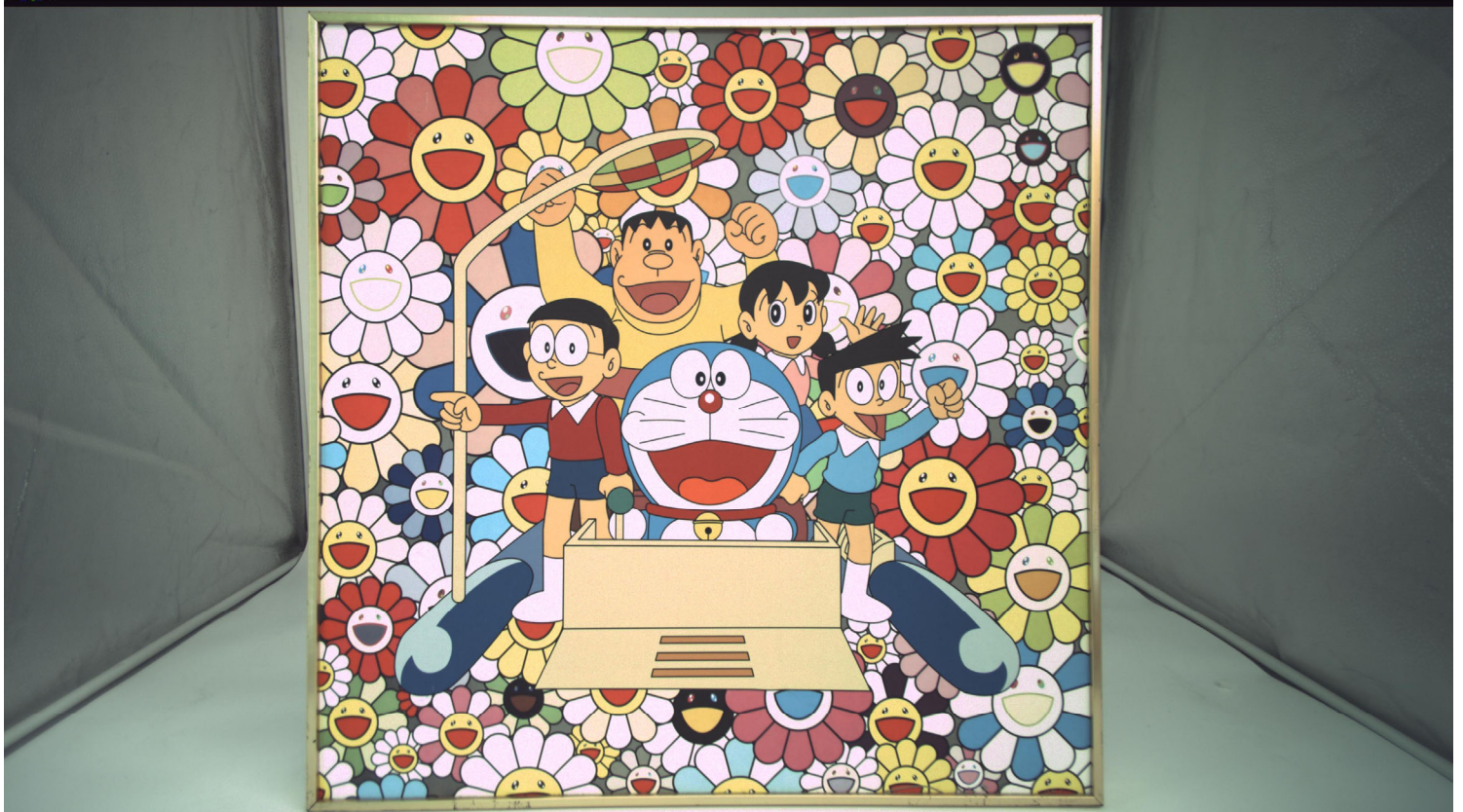


Bottom View


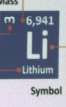



Mating Connector





Periodic table of Elements

Legend:

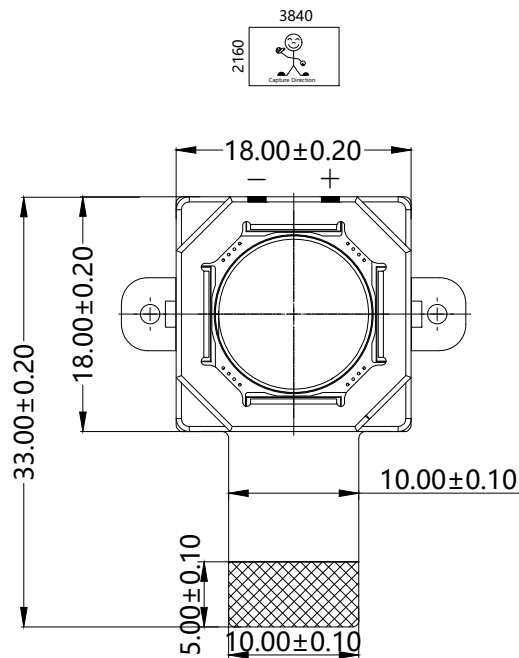
- Hydrogen (Gas)
- Alkali Metals
- Alkaline Earth Metals
- Transition Metals
- Other Metals
- Metalloids
- Non-metals
- Halogens
- Noble Gases
- Lanthanides
- Actinides

GROUP	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
PERIOD 1	1, 1.008 H Hydrogen	2, 4.002 He Helium																
PERIOD 2	3, 6.941 Li Lithium	4, 9.01 Be Beryllium																
PERIOD 3	11, 22.99 Na Sodium	12, 24.31 Mg Magnesium																
PERIOD 4	19, 39.09 K Potassium	20, 40.08 Ca Calcium	21, 44.95 Sc Scandium	22, 47.87 Ti Titanium	23, 50.94 V Vanadium	24, 51.99 Cr Chromium	25, 54.94 Mn Manganese	26, 55.85 Fe Iron	27, 58.93 Co Cobalt	28, 58.69 Ni Nickel	29, 63.55 Cu Copper	30, 65.39 Zn Zinc	31, 69.72 Ga Gallium	32, 72.61 Ge Germanium	33, 74.92 As Arsenic	34, 78.96 Se Selenium	35, 79.90 Br Bromine	36, 83.80 Kr Krypton
PERIOD 5	37, 85.47 Rb Rubidium	38, 87.62 Sr Strontium	39, 88.91 Y Yttrium	40, 91.22 Zr Zirconium	41, 92.91 Nb Niobium	42, 95.94 Mo Molybdenum	43, 97 Tc Technetium	44, 101.1 Ru Ruthenium	45, 102.9 Rh Rhodium	46, 106.4 Pd Palladium	47, 107.9 Ag Silver	48, 112.4 Cd Cadmium	49, 114.8 In Indium	50, 118.7 Sn Tin	51, 121.8 Sb Antimony	52, 127.6 Te Tellurium	53, 126.9 I Iodine	54, 131.3 Xe Xenon
PERIOD 6	55, 132.9 Cs Cesium	56, 137.3 Ba Barium	57-71 Lanthanides	72, 178.5 Hf Hafnium	73, 180.9 Ta Tantalum	74, 183.8 W Tungsten	75, 186.2 Re Rhenium	76, 190.2 Os Osmium	77, 192.2 Ir Iridium	78, 195.1 Pt Platinum	79, 196.9 Au Gold	80, 200.6 Hg Mercury	81, 204.4 Tl Thallium	82, 207.2 Pb Lead	83, 208.9 Bi Bismuth	84, (210) Po Polonium	85, (210) At Astatine	86, (222) Rn Radon
PERIOD 7	87, (223) Fr Francium	88, (226) Ra Radium	89-103 Actinides	104, (261) Rf Rutherfordium	105, (262) Db Dubnium	106, (263) Sg Seaborgium	107, (264) Bh Bohrium	108, (265) Hs Hassium	109, (268) Mt Meitnerium	110, (281) Ds Darmstadtium	111, (280) Rg Roentgenium	112, (285) Cn Copernicium	113, (284) Nh Nihonium	114, (289) Fl Flerovium	115, (288) Mc Moscovium	116, (292) Lv Livermorium	117, (294) Ts Tennessine	118, (294) Og Oganesson
PERIOD 8	89, (232) Ac Actinium	90, (232) Th Thorium	91, (231) Pa Protactinium	92, (238) U Uranium	93, (239) Np Neptunium	94, (239) Pu Plutonium	95, (243) Am Americium	96, (247) Cm Curium	97, (251) Bk Berkelium	98, (251) Cf Californium	99, (257) Es Einsteinium	100, (257) Fm Fermium	101, (258) Md Mendelevium	102, (259) No Nobelium	103, (260) Lr Lawrencium			

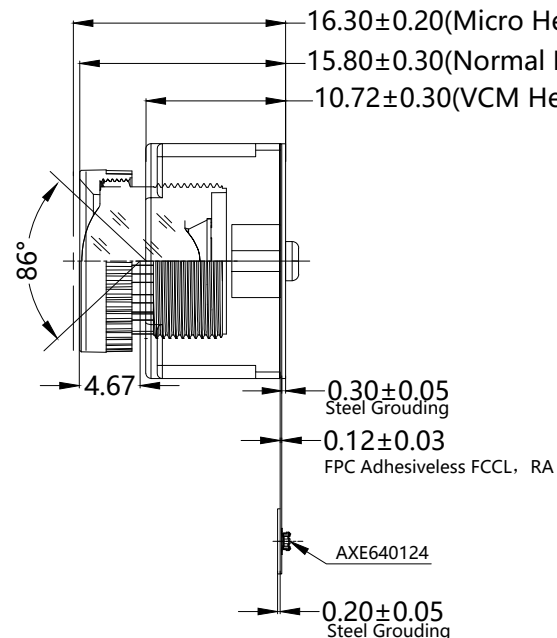


PIN	SIGNAL
1	NC
2	PWDN
3	DGND
4	DMO1P
5	DMO1N
6	DGND
7	DMO2P
8	DMO2N
9	DGND
10	DMO3P
11	DMO3N
12	DGND
13	DMO4P
14	DMO4N
15	DGND
16	DCKP
17	DCKN
18	NC
19	NC
20	NC
21	NC
22	NC
23	NC
24	NC
25	SCL
26	SDA
27	DGND
28	INCK
29	DVDD 1.2V
30	DOVDD 1.8V
31	DGND
32	AVDD 2.8V
33	AGND
34	DGND
35	AFVDD 2.8V
36	NC
37	NC
38	NC
39	DGND
40	DGND

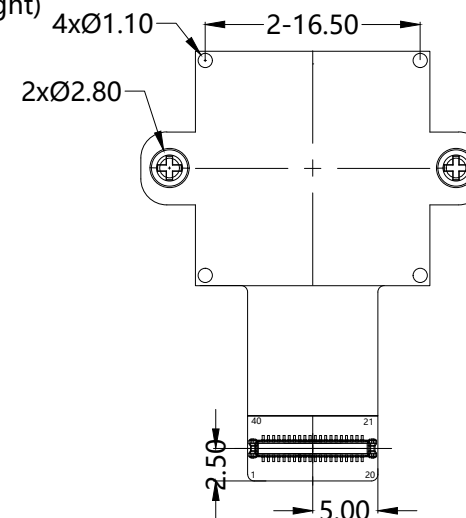
Version	Information
V1.0	First Version



TOP VIEW



SIDE VIEW



BOTTOM VIEW

NOTE:

- 1.VCM driver IC: DW9714P;
- 2.Sensor I2C slave address: 0x34

Parameters:

1、Sensor specification:

Image Sensor: IMX317CQC-C

Pixel: 1.62um*1.62um

Lens Type: 1/2.5

Important Voltage Description:

DVDD1.2V (external power supply);

2、Lens specification:

FOV: 85.8°(D);77.5°(H);48.8°(V);

F/NO.: 2.2

TV distortion: <-0.4%

Focal length: 3.38mm

Composition: 1G4P+IR FILTER

IR Cut Coating: 650nm±10nm@50%

Kai Lap Technologies Group Ltd

Designed By

Kevin

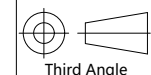
Model Name:

KLT-MAA44-IMX317 V1.0

Checked By

Jacky

Projection Type:



Unit:

mm

Date:

10/14/2025

Scale:

1:1

Sheet:

1 of 1

Version:

1/0

[Product Information]

Ver.1.0

IMX317CQC

Diagonal 7.20 mm (Type 1/2.5) CMOS Image Sensor with Square Pixel for Color Cameras

Description

The IMX317CQC is a diagonal 7.20 mm (Type 1/2.5) CMOS image sensor with a color square pixel array and approximately 8.51 M effective pixels. 12-bit digital output makes it possible to output the signals of approximately 8.51 M effective pixels with high definition for shooting still pictures. It also operates with three power supply voltages: analog 2.8 V, digital 1.2 V, and 1.8 V for I/O interface and achieves low power consumption. Furthermore, it realizes 12-bit digital output for shooting high-speed and high-definition moving pictures by horizontal and vertical addition and subsampling. Realizing high-sensitivity, low dark current, this sensor also has an electronic shutter function with variable storage time.

In addition, this product is designed for use in consumer use digital still camera and consumer use camcorder. When using this for another application, Sony Semiconductor Solutions Corporation does not guarantee the quality and reliability of the product. Therefore, don't use this for applications other than consumer use digital still camera and consumer use camcorder.

In addition, individual specification change cannot be supported because this is a standard product.

Consult your Sony Semiconductor Solutions Corporation sales representative if you have any questions.

Features

- ◆ CMOS active pixel type pixels
- ◆ Input clock frequency 6 to 27 MHz (CSI-2), 12/24/36/72 MHz (Sub-LVDS)
- ◆ Both MIPI Specifications (CSI-2 high-speed serial interface) and Sub-LVDS supported
- ◆ All-pixel scan mode
 - Various readout modes (*)
- ◆ High-sensitivity, low dark current, no smear, excellent anti-blooming characteristics
- ◆ Vertical and horizontal arbitrary cropping function
- ◆ Variable-speed shutter function (minimum unit: 1 horizontal period)
- ◆ Low power consumption
- ◆ Digital Overlap High Dynamic Range (DOL-HDR) function
- ◆ H driver, V driver and serial communication circuit on chip
- ◆ CDS/PGA on chip: Gain +27 dB (step pitch 0.1 dB)
- ◆ 10-bit/12-bit A/D conversion on chip
- ◆ R, G, B primary color mosaic filters on chip
- ◆ All-pixel simultaneous reset supported
- ◆ 92-pin high-precision ceramic package

* Please refer to the datasheet for binning/subsampling details of readout modes.

Sony reserves the right to change products and specifications without prior notice.
Sony logo is a registered trademark of Sony Corporation.

Device Structure

◆ CMOS image sensor	
◆ Image size	Diagonal 7.20 mm (Type 1/2.5)
◆ Total number of pixels	3864 (H) × 2218 (V) approx. 8.57 M pixels
◆ Number of effective pixels	3864 (H) × 2202 (V) approx. 8.51 M pixels
◆ Number of active pixels	3864 (H) × 2196 (V) approx. 8.49 M pixels diagonal 7.20 mm
◆ Number of recommended recording pixels	3840 (H) × 2160 (V) 8.29 M pixels aspect ratio 16:9
◆ Chip size	8.365 mm (H) × 6.615 mm (V) (include scribe area)
◆ Unit cell size	1.62 μm (H) × 1.62 μm (V)
◆ Optical black	Horizontal (H) direction: Front 0 pixel, Rear 0 pixel Vertical (V) direction: Front 16 pixels, Rear 0 pixel
◆ Package	92 pin LGA

Image Sensor Characteristics

(T_j = 60 °C)

Item		Value	Remarks
Sensitivity (F5.6)	Typ.	1145 digit	1/30 s integration
Saturation signal	Min.	3050 digit	

Basic Drive Mode

Drive mode	Number of recording pixels	Max frame rate [frame/s]		Output data bit length [bit]
		CSI-2	Sub-LVDS	
Readout mode 0	3840 (H) × 2160 (V) approx. 8.29 M pixels	32.81	32.73	12
Readout mode 1	3840 (H) × 2160 (V) approx. 8.29 M pixels	62.52	62.06	10
Readout mode 2	1920 (H) × 1080 (V) approx. 2.07 M pixels	65.82	65.61	12
Readout mode 3	1920 (H) × 1080 (V) approx. 2.07 M pixels	124.80	124.40	10
Readout mode 4	1920 (H) × 1080 (V) approx. 2.07 M pixels	124.80	124.40	10
Readout mode 5	1280 (H) × 720 (V) approx. 0.92 M pixels	185.73	184.86	10
Readout mode 6	1280 (H) × 540 (V) approx. 0.69 M pixels	249.26	247.70	10

FEATURES

120mA output driver with 10-bit resolution DAC
Smart Actuator Control (SAC™) modes
Supply voltage (V_{DD}): 2.3V to 4.3V
I/O voltage (V_{IN}): 1.8V to V_{DD}
Fast mode and Fast mode plus I²C interface compatible
Power On Reset (POR)
Power Down (PD) mode current consumption less than 1uA
Package: 6-pin WLCSP (0.77mm x 1.14mm x 0.30mm)

APPLICATIONS

Mobile camera
Digital still camera
Camcorder
Web camera
Action camera

GENERAL DESCRIPTION

The DW9714P designed for linear control of Voice Coil Motors (VCM). This device is compatible with DW9714. The DW9714P has a single 10-bit DAC with 120mA output current sink capability. This device features SAC™ mode which can minimize the mechanical vibration and achieve very fast mechanical settling time. The SAC™ is protected by patent and registered trademark of DONGWOON ANATECH.

The DW9714P operates from a single 2.3V to 4.3V supply. The internal DAC is controlled via an I²C serial interface that operates at clock rate up to 1MHz. The I²C address for the DW9714P is 0x18. The DW9714P offers PD mode with current consumption less than 1uA.

The DW9714P can be used for auto focus applications in mobile cameras, digital still cameras, camcorders, web cameras and action cameras.

TYPICAL APPLICATION CIRCUIT

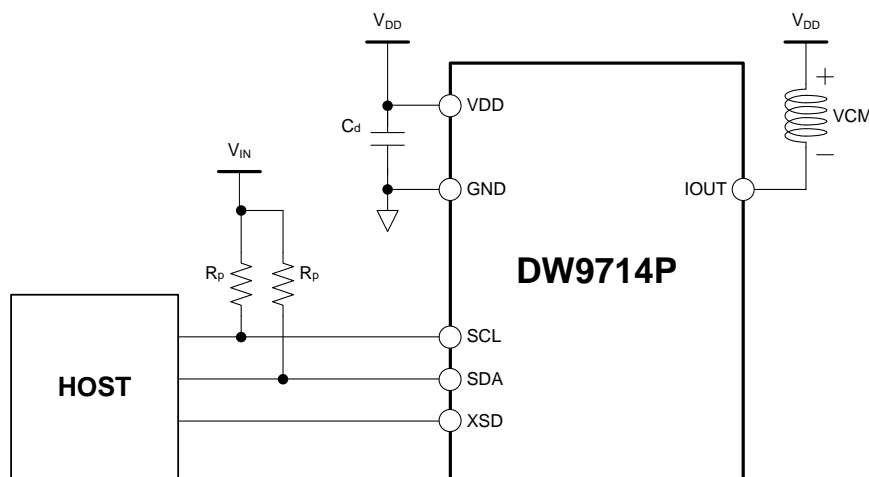
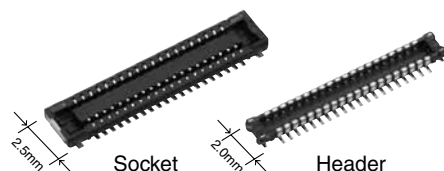


Figure 1. Typical application circuit



RoHS compliant

For board-to-FPC

**Narrow pitch connectors
(0.4mm pitch)**

A4S Series

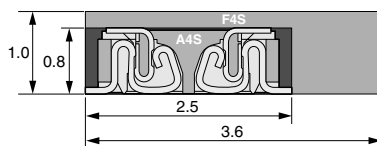
FEATURES

1. 2.5 mm wide slim two-piece style connectors

Compact and slim structure contributes overall miniaturization of product design.

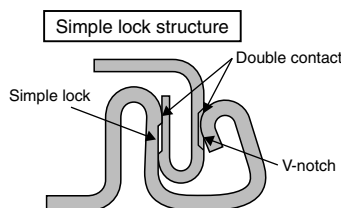
<Compared to F4S series (40 pin contacts, when mated)>

- Width: 30% down
- Footprint: 30% down



2. “**TOUGH CONTACT ADVANCED**” ensures high resistance to various environments in lieu of slim and low profile body

3. Simple lock structure provides tactile feedback to ensure excellent mating/unmating operation feel.



The connector gives the tactile feedback when inserted, allowing reliable mating.

4. Mated heights of 0.8 and 1.0 mm are available for the same foot pattern.

5. Connectors for inspection available

APPLICATIONS

Recommended for board-to-FPC connections of mobile equipment, such as cellular phones, smart phones, laptops, and portable music players

ORDERING INFORMATION

5: Narrow Pitch Connector A4S (0.4 mm pitch) Socket
6: Narrow Pitch Connector A4S (0.4 mm pitch) Header

Number of pins (2 digits)

Mated height

<Socket>

1: For mated height 0.8/1.0 mm

<Header>

1: For mated height 0.8 mm

2: For mated height 1.0 mm

Functions

2: Without positioning bosses

Surface treatment (Contact portion / Terminal portion)

<Socket>

4: Ni plating on base, Au plating on surface (for Ni barrier available)

<Header>

4: Ni plating on base, Au plating on surface

AXE

2

4

PRODUCT TYPES

Mated height	Number of pins	Part number		Packing	
		Socket	Header	Inner carton (1-reel)	Outer carton
0.8mm	10	AXE510124	AXE610124	5,000 pieces	10,000 pieces
	12	AXE512124	AXE612124		
	14	AXE514124	AXE614124		
	16	AXE516124	AXE616124		
	18	AXE518124	AXE618124		
	20	AXE520124	AXE620124		
	22	AXE522124	AXE622124		
	24	AXE524124	AXE624124		
	26	AXE526124	AXE626124		
	28	AXE528124	AXE628124		
	30	AXE530124	AXE630124		
	32	AXE532124	AXE632124		
	34	AXE534124	AXE634124		
	36	AXE536124	AXE636124		
	38	AXE538124	AXE638124		
	40	AXE540124	AXE640124		
	44	AXE544124	AXE644124		
	50	AXE550124	AXE650124		
	54	AXE554124	AXE654124		
	56	AXE556124	AXE656124		
1.0mm	60	AXE560124	AXE660124	5,000 pieces	10,000 pieces
	64	AXE564124	AXE664124		
	70	AXE570124	AXE670124		
	80	AXE580124	AXE680124		
	10	AXE510124	AXE610224		
	12	AXE512124	AXE612224		
	14	AXE514124	AXE614224		
	20	AXE520124	AXE620224		
	24	AXE524124	AXE624224		
	26	AXE526124	AXE626224		
	30	AXE530124	AXE630224		
	32	AXE532124	AXE632224		
	40	AXE540124	AXE640224		
	44	AXE544124	AXE644224		
	50	AXE550124	AXE650224		
	54	AXE554124	AXE654224		
	60	AXE560124	AXE660224		
	70	AXE570124	AXE670224		
	80	AXE580124	AXE680224		

Notes: 1. Order unit:

For volume production: 1-inner carton (1-reel) units

Samples for mounting check: 50-connector units. Please contact our sales office.

Samples: Small lot orders are possible. Please contact our sales office.

2. The above part numbers are for connectors without positioning bosses, which are standard. When ordering connectors with positioning bosses, please contact our sales office.

3. Please contact us for connectors having a number of pins other than those listed above.

SPECIFICATIONS

■ Characteristics

	Item	Specifications	Conditions
Electrical characteristics	Rated current	0.3A/pin contact (Max. 5 A at total pin contacts)	
	Rated voltage	60V AC/DC	
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1.000MΩ (initial)	Using 250V DC megger (applied for 1 min.)
	Contact resistance	Max. 90mΩ	Based on the contact resistance measurement method specified by JIS C 5402.
Mechanical characteristics	Composite insertion force	Max. 1.200N/pin contacts × pin contacts (initial)	
	Composite removal force	Min. 0.165N/pin contacts × pin contacts	
	Contact holding force (Socket contact)	Min. 0.20N/pin contacts	Measuring the maximum force. As the contact is axially pull out.
Environmental characteristics	Ambient temperature	−55°C to +85°C	No freezing at low temperatures. No dew condensation.
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals) 300°C within 5 sec. 350°C within 3 sec.	Infrared reflow soldering Soldering iron
	Storage temperature	−55°C to +85°C (product only) −40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Sequence 1. −55.0°C, 30 minutes 2. ~, Max. 5 minutes 3. 85.0°C, 30 minutes 4. ~, Max. 5 minutes
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 40±2°C, humidity 90 to 95% R.H.
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 35±2°C, saltwater concentration 5±1%
	H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. 90mΩ	Bath temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.
Lifetime characteristics	Insertion and removal life	30 times	Repeated insertion and removal speed of max. 200 times/hours
Unit weight		20 pin contact type: Socket: 0.02 g Header: 0.01 g	

■ Material and surface treatment

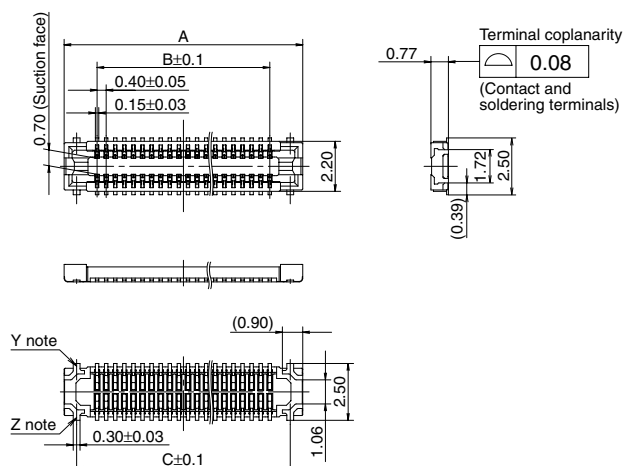
Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	—
Contact and Post	Copper alloy	Contact portion: Base: Ni plating Surface: Au plating Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Soldering terminals: Sockets: Base: Ni plating Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating Surface: Au plating (except the terminal tips)

DIMENSIONS (Unit: mm)

The CAD data of the products with a **CAD Data** mark can be downloaded from: <http://industrial.panasonic.com/ac/e>

■ Socket (Mated height: 0.8 mm/1.0 mm)

CAD Data



General tolerance: ±0.2

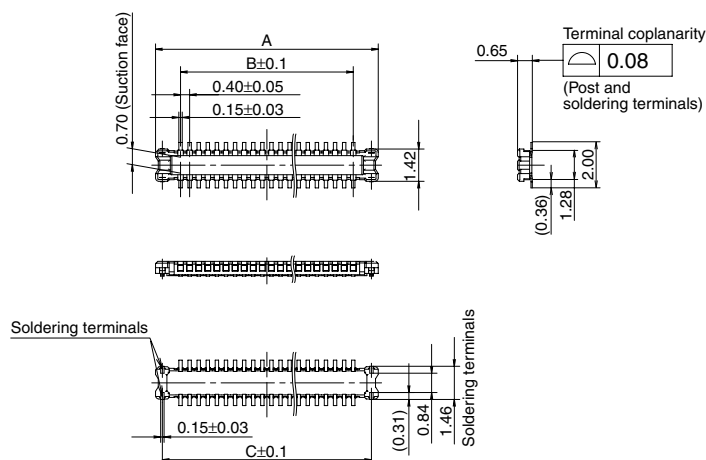
Note: Since the soldering terminals has a single-piece construction, sections Y and Z are electrically connected.

Dimension table (mm)

Number of pins/ dimension	A	B	C
10	4.5	1.6	3.4
12	4.9	2.0	3.8
14	5.3	2.4	4.2
16	5.7	2.8	4.6
18	6.1	3.2	5.0
20	6.5	3.6	5.4
22	6.9	4.0	5.8
24	7.3	4.4	6.2
26	7.7	4.8	6.6
28	8.1	5.2	7.0
30	8.5	5.6	7.4
32	8.9	6.0	7.8
34	9.3	6.4	8.2
36	9.7	6.8	8.6
38	10.1	7.2	9.0
40	10.5	7.6	9.4
44	11.3	8.4	10.2
50	12.5	9.6	11.4
54	13.3	10.4	12.2
56	13.7	10.8	12.6
60	14.5	11.6	13.4
64	15.3	12.4	14.2
70	16.5	13.6	15.4
80	18.5	15.6	17.4

■ Header (Mated height: 0.8 mm)

CAD Data



General tolerance: ±0.2

Dimension table (mm)

Number of pins/ dimension	A	B	C
10	3.8	1.6	3.2
12	4.2	2.0	3.6
14	4.6	2.4	4.0
16	5.0	2.8	4.4
18	5.4	3.2	4.8
20	5.8	3.6	5.2
22	6.2	4.0	5.6
24	6.6	4.4	6.0
26	7.0	4.8	6.4
28	7.4	5.2	6.8
30	7.8	5.6	7.2
32	8.2	6.0	7.6
34	8.6	6.4	8.0
36	9.0	6.8	8.4
38	9.4	7.2	8.8
40	9.8	7.6	9.2
44	10.6	8.4	10.0
50	11.8	9.6	11.2
54	12.6	10.4	12.0
56	13.0	10.8	12.4
60	13.8	11.6	13.2
64	14.6	12.4	14.0
70	15.8	13.6	15.2
80	17.8	15.6	17.2

Cameras Applications



Automotive Driver Pilot



Live Streaming



Video Conference



Eye Tracker Biometric Detection



Machine Vision



Agricultural Monitor



Night Vision Security



Drone and Sports Eagle Eyes



Interactive Pet Camera



Cameras Applications

your BEST camera module partner



IMAGING DEVICES



Camera Module Pinout Definition Reference Chart

OmniVision Sony Samsung On-Semi Aptina Himax GalaxyCore PixArt SmartSens Sensors	
Pin Signal	Description
DGND GND	ground for digital circuit
AGND	ground for analog circuit
PCLK DCK	DVP PCLK output
XCLR PWDN XSHUTDOWN STANDBY	power down active high with internal pull-down resistor
MCLK XVCLK XCLK INCK	system input clock
RESET RST	reset active low with internal pull-up resistor
NC NULL	no connect
SDA SIO_D SIOD	SCCB data
SCL SIO_C SIOC	SCCB input clock
VSYNC XVS FSYNC	DVP VSYNC output
HREF XHS	DVP HREF output
DOVDD	power for I/O circuit
AFVDD	power for VCM circuit
AVDD	power for analog circuit
DVDD	power for digital circuit
STROBE FSTROBE	strobe output
FSIN	synchronize the VSYNC signal from the other sensor
SID	SCCB last bit ID input
ILPWM	mechanical shutter output indicator
FREX	frame exposure / mechanical shutter
GPIO	general purpose inputs
SLASEL	I2C slave address select
AFEN	CEN chip enable active high on VCM driver IC
MIPI Interface	
MDN0 DN0 MD0N DATA_N DMO1N	MIPI 1st data lane negative output
MDP0 DP0 MD0P DATA_P DMO1P	MIPI 1st data lane positive output
MDN1 DN1 MD1N DATA2_N DMO2N	MIPI 2nd data lane negative output
MDP1 DP1 MD1P DATA2_P DMO2P	MIPI 2nd data lane positive output
MDN2 DN2 MD2N DATA3_N DMO3N	MIPI 3rd data lane negative output
MDP2 DP2 MD2P DATA3_P DMO3P	MIPI 3rd data lane positive output
MDN3 DN3 MD3N DATA4_N DMO4N	MIPI 4th data lane negative output
MDP3 DP3 MD3P DATA4_P DMO4P	MIPI 4th data lane positive output
MCN CLKN CLK_N DCKN	MIPI clock negative output
MCP CLKP MCP CLK_P DCKN	MIPI clock positive output
DVP Parallel Interface	
D0 DO0 Y0	DVP data output port 0
D1 DO1 Y1	DVP data output port 1
D2 DO2 Y2	DVP data output port 2
D3 DO3 Y3	DVP data output port 3
D4 DO4 Y4	DVP data output port 4
D5 DO5 Y5	DVP data output port 5
D6 DO6 Y6	DVP data output port 6
D7 DO7 Y7	DVP data output port 7
D8 DO8 Y8	DVP data output port 8
D9 DO9 Y9	DVP data output port 9
D10 DO10 Y10	DVP data output port 10
D11 DO11 Y11	DVP data output port 11

Camera Reliability Test

Reliability Inspection Item			Testing Method	Acceptance Criteria
Category		Item		
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional



Inspection Item			Inspection Method	Standard of Inspection	
Category		Item			
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.	
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.	
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)	
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed	
		Gap	The Naked Eye	Meet the Height Standard	
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)	
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed	
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard	
		Contamination	The Naked Eye	No Effect On Resolution Standard	
		Oil Film	The Naked Eye	No Effect On Resolution Standard	
		Cover Tape	The Naked Eye	No Issue On Appearance.	
	Function	Image	No Communication	Test Board	Not Allowed
			Bright Pixel	Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center	
Blurry			The Naked Eye	Not Allowed	
No Image			The Naked Eye	Not Allowed	
Vertical Line			The Naked Eye	Not Allowed	
Horizontal Line			The Naked Eye	Not Allowed	
Light Leakage			The Naked Eye	Not Allowed	
Blinking Image			The Naked Eye	Not Allowed	
Bruise			Inspection Jig	Not Allowed	
Resolution			Chart	Follows Outgoing Inspection Chart Standard	
Color			The Naked Eye	No Issue	
Noise			The Naked Eye	Not Allowed	
Corner Dark			The Naked Eye	Less Than 100px By 100px	
Color Resolution			The Naked Eye	No Issue	
Dimension			Height	The Naked Eye	Follows Approval Data Sheet
		Width	The Naked Eye	Follows Approval Data Sheet	
		Length	The Naked Eye	Follows Approval Data Sheet	
		Overall	The Naked Eye	Follows Approval Data Sheet	

KLT Package Solutions

KLT Camera Module



Complete with Lens Protection Film



Tray with Grid and Space



Place Cameras on the Tray



Camera Modules Package Solution

Full Tray of Cameras



Cover Tray with Lid



Put Tray into Anti-Static Bag



Vacuum the Anti-Static Bag



Camera Modules Package Solution

Sealed Vacuum Bag with Labels

1. Model and Description 2. Quantity 3. Shipping Date 4. Caution



Large Order Package Solution

Place Foam Sheets Between Trays



Foam Sheets are Slightly Larger than Trays



Place Foam Sheets and Trays into Box



Foam Sheets are Tightly Fitting Box



Small Order Package Solution

Place Foam Sheets and Trays into Small Box



Foam Sheets are Nicely Fitting the Small Box



Package in Small Box for Shipment



Place Small Boxes into Larger Box



Carbon Box Package Solution

Seal the Carbon Box

Final Package Labelled Box



Carbon Box Ready for Shipment

1. Delivery Address and Phone No. 2. Box No. and Ship Date 3. Fragile Caution



Sample Order Package Solution

Place Sample into Small Anti-Static Bag



Place Connectors into Small Ant-Static Bag



Sample Labels on the Small Bag

1. Camera Module or Connector Model 2. Shipping Date and Quantity 3. Caution



Connectors Large Order Package Solution

Connectors in a Wheel



Label Connectors in the Wheel



The Wheel is Perfectly Fitting the Box



Connectors Box Ready for Shipment





CMOS CAMERA MODULES



your BEST camera module partner

Company Kai Lap Technologies (KLT)

Kai Lap Technologies Group Limited. (KLT) was established in 2009, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. KLT is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

KLT provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. KLT specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.



Limited Warranty

KLT provides the following limited warranty if you purchased the Product(s) directly from KLT company or from KLT's website, www.KaiLapTech.com. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. KLT guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, KLT will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of KLT is solely limited to repair and/or replacement on the terms set forth above. KLT is not reliable or responsible for any subsequent events.



www.KaiLapTech.com sales@KaiLapTech.com Tel: (852) 6908 1256 Fax: (852) 3017 6778



CMOS CAMERA MODULES



your BEST camera module partner

KLT Strength

Powerful Factory



Professional Service



Promised Delivery



www.KaiLapTech.com sales@KaiLapTech.com Tel: (852) 6908 1256 Fax: (852) 3017 6778

All rights reserved @ Kai Lap Technologies Group Ltd. Specifications subject to change without notice.